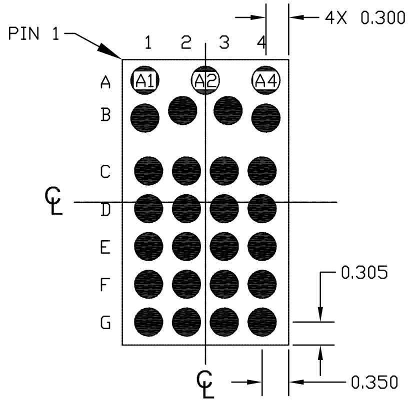
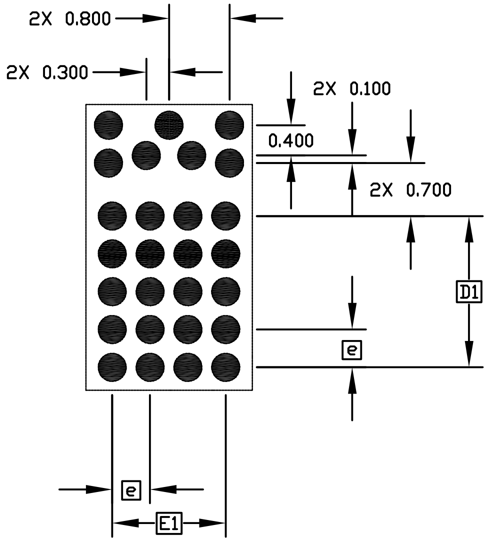
PACKAGE OVERLAY

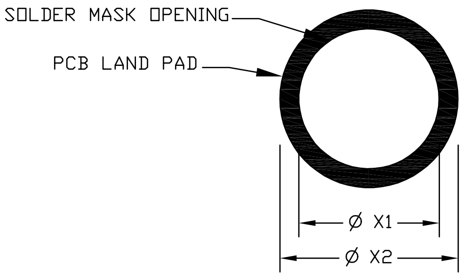


	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
D1	2.000 BSC			.07874 BSC		
E1	1.500 BSC			.05906 BSC		
e	0.500 BSC			.01969 BSC		
N	27 BALLS			27 BALLS		

RECOMMENDED LAND PATTERN



PAD DETAIL INFORMATION



	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
X1	0.230	0.280	0.330	.00906	.01102	.01299
X2	0.360	-	-	.01417	-	-

NOTES:

1. REFERENCE PKG. OUTLINE: 21-0928
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
4. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-

maxim integrated™

This document (including dimensions, notes & specs) is a recommendaton based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use.
This document is subject to change without notice.
Contact technical support at http://www.maximintegrated.com/support for further questions.

TITLE:
PACKAGE LAND PATTERN,
[C272C3+1] WLCSP

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